

RoHS Compliant HF

REV.	ECN.NO.	MODIFY.CONTENT
X1	2023-03-14	NEW

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A.
- 2.2 VOLTAGE RATING: 50V.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 500MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

FB01-080MXXXXXX4XX

Pin 数码	塑胶高度:	11: Au 15u"
SEE TABLE	068=6.80mm ("H1")	12: Au 30u"
010=2x05PIN	078=7.80mm ("H1")	
~		
120=2x60PIN		

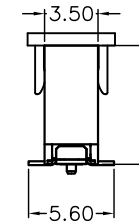
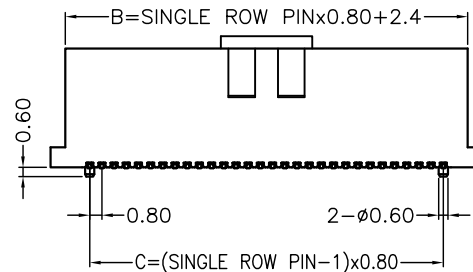
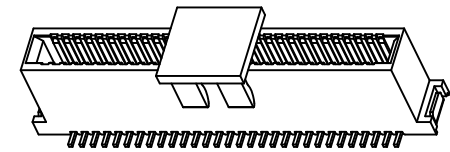
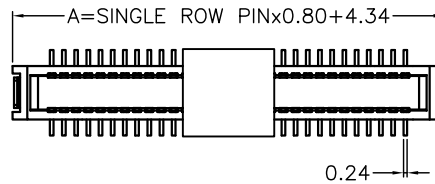
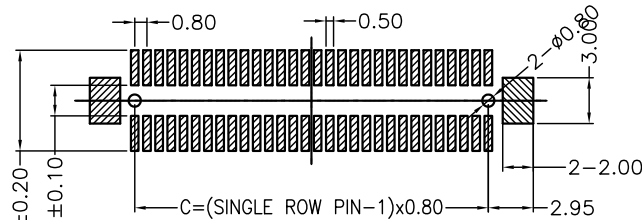
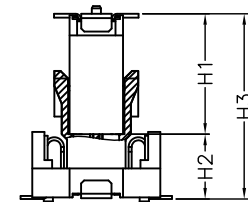


TABLE1:

No.OF PIN	Dimensions		
	A	B	C
010=2*05PIN	8.34	6.40	3.20
020=2*10PIN	12.34	10.40	7.20
030=2*15PIN	16.34	14.40	11.20
040=2*20PIN	20.34	18.40	15.20
050=2*25PIN	24.30	22.40	19.20
060=2*30PIN	28.34	26.40	23.20
080=2*40PIN	36.34	34.40	31.20
100=2*50PIN	44.34	42.40	39.20
120=2*60PIN	52.34	50.40	47.20



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



MATING HEIGHT

MATING HEIGHT	H1	H2	H3
11.75mm	6.80	4.95	11.75
12.75mm	7.80		12.75

GENERAL TOLERANCE	DWG.NO.	F B01-080MXXXXXX400	PART.NO.	F B01-080MXXXXXX4XX	DRAWN	Brian 2023-03-14
x.±0.50	REV.	X1	TITLE	浮动板对板0.8Pitch公座	CHECKED	
.x±0.25	SIZE	A4	SHEET	1 OF 1	APPROVED	
.xx±0.15						

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			